

TOSHIBA LED LAMP GaP GREEN LIGHT EMISSION

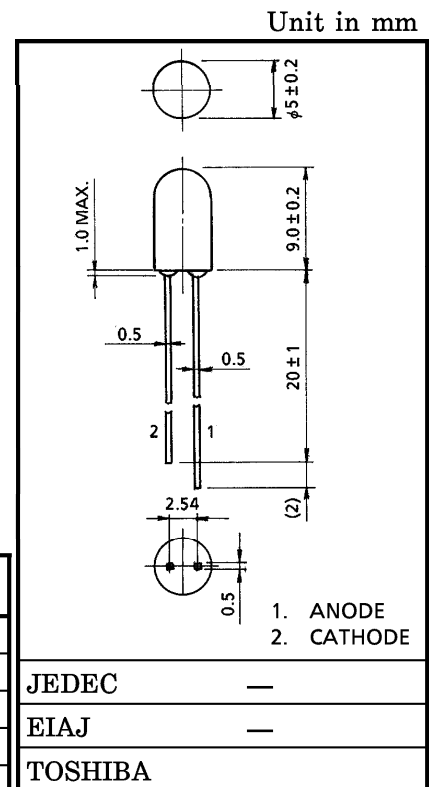
TLGC245P

PANEL CIRCUIT INDICATOR

- 5mm DIAMETER (T1-3 / 4) FLANGELESS PACKAGE
- All Plastic Mold Type Colorless Clear Lens
- Low Drive Current, High Intensity Green Light Emission.
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Without stand-offs
- Fast Response Time, Capable of Pulse Operation.
- High Power Luminous Intensity
Suitable for Outdoor Message Signboard.

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current	I_F	40	mA
Reverse Voltage	V_R	4	V
Power Dissipation	P_D	120	mW
Operating Temperature Range	T_{opr}	-20~85	°C
Storage Temperature Range	T_{stg}	-30~100	°C



Weight : 0.31g

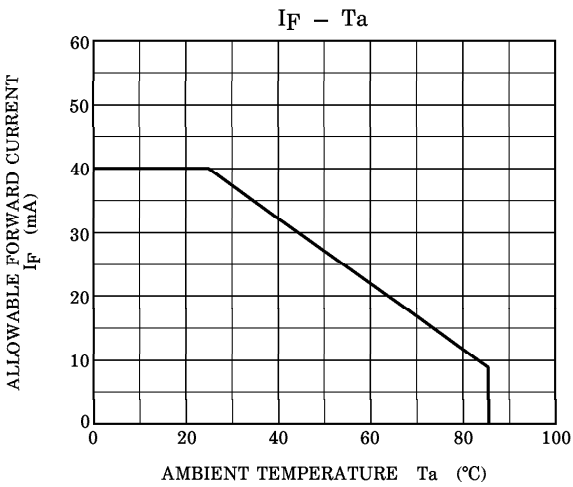
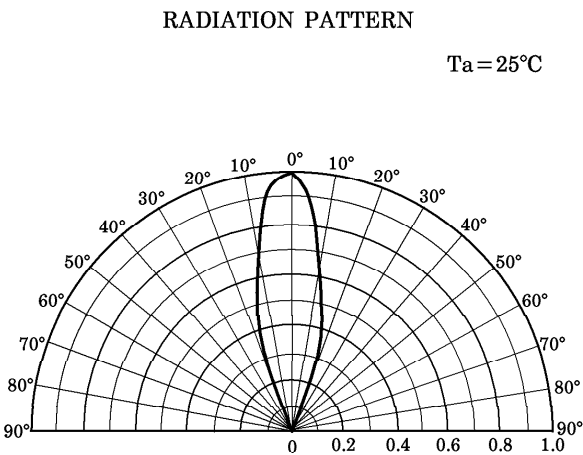
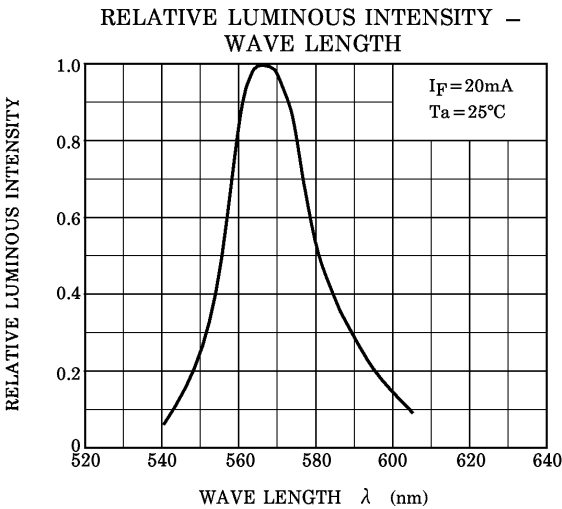
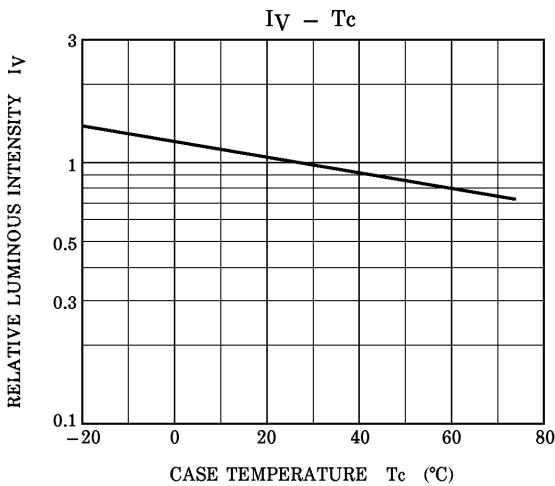
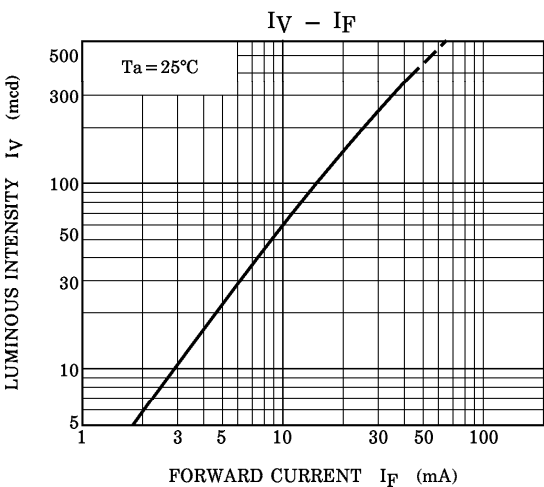
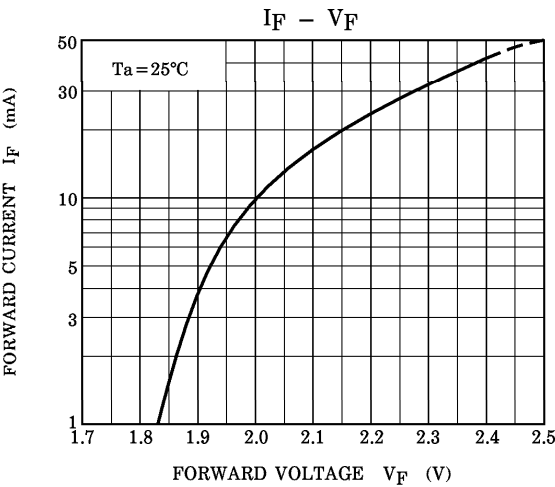
ELECTRO-OPTICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	V_F	$I_F = 20\text{mA}$	—	2.15	2.8	V
Reverse Current	I_R	$V_R = 4\text{V}$	—	—	5	μA
Luminous Intensity	I_V	$I_F = 20\text{mA}$	47.6	150	—	mcd
Peak Emission Wave Length	λ_p	$I_F = 20\text{mA}$	—	567	—	nm
Spectral Line Half Width	$\Delta\lambda$	$I_F = 20\text{mA}$	—	25	—	nm

PRECAUTION

Please be careful of the followings

- Soldering temperature : 260°C MAX. Soldering time : 3s MAX.
(Soldering portion of lead : up to 2mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.



RESTRICTIONS ON PRODUCT USE

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